

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t3973hdd-5#pbf

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

(printed on: 2020-07-11 20:35:54)

**TOTAL MASS (g) : 0.023425**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001326	1000000	56605.3125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.009711	975000	414550.6875		
		Iron (Fe)	7439-89-6	0.000239	24000	10202.6162109		
		Phosphorus (P)	7723-14-0	0.000003	300	128.066329956		
		Zinc (Zn)	7440-66-6	0.000007	700	298.821411133		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.009960</b>	<b>1000000</b>	<b>425180.1875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000455	1000000	19438.8730469		
		<b>External Plating Total:</b>				<b>0.000455</b>	<b>1000000</b>	<b>19438.8730469</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000225	1000000	9604.97363281		
<b>Internal Plating Total:</b>				<b>0.000225</b>	<b>1000000</b>	<b>9604.97363281</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000684	750000	29199.1210938		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000228	250000	9733.04101562		
<b>Die Attach Total:</b>				<b>0.000912</b>	<b>1000000</b>	<b>38932.1640625</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001362	130000	58142.109375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.009013	860000	384753.90625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000105	10000	4482.32080078		
		<b>Encapsulation Total:</b>				<b>0.010480</b>	<b>1000000</b>	<b>447378.34375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000067	1000000	2860.14770508		
					<b>TOTAL MASS (g) :</b>	<b>0.023425</b>		